

# EQRA22F2H-18.4875M

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## REGULATORY COMPLIANCE (Data Sheet downloaded on Feb 17, 2020)


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## ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 2.5Vdc 6 Pad 3.2mm x 5.0mm Ceramic Surface Mount (SMD) 18.4875MHz  $\pm 50$ ppm over  $-20^{\circ}\text{C}$  to  $+70^{\circ}\text{C}$

## ELECTRICAL SPECIFICATIONS

Nominal Frequency	18.4875MHz
Frequency Tolerance/Stability	$\pm 50$ ppm Maximum over $-20^{\circ}\text{C}$ to $+70^{\circ}\text{C}$ (Inclusive of all conditions: Calibration Tolerance (at $25^{\circ}\text{C}$ ), Frequency Stability over the Operating Temperature Range, Supply Voltage Change and Output Load Change)
Aging at $25^{\circ}\text{C}$	$\pm 2$ ppm Maximum First Year, $\pm 10$ ppm/10 Years Maximum
Supply Voltage	2.5Vdc $\pm 5\%$
Input Current	20mA Maximum (Unloaded)
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH = -4mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL = +4mA)
Rise/Fall Time	3nSec Maximum (Measured at 10% to 90% of Waveform)
Duty Cycle	50 $\pm 5$ (%) (Measured at 50% of Waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Phase Noise	-64dBc/Hz at 10Hz offset; -96dBc/Hz at 100Hz offset; -124dBc/Hz at 1kHz offset; -131dBc/Hz at 10kHz offset; -132dBc/Hz at 100kHz offset; -149dBc/Hz at 1MHz offset; -157dBc/Hz at 10MHz offset; -159dBc/Hz at 20MHz offset (All Values are Typical)
Output Control Function	Output Enable (OE)
Output Control Input Voltage Logic High (Vih)	90% of Vdd Minimum or No Connect to Enable Output
Output Control Input Voltage Logic Low (Vil)	10% of Vdd Maximum to Disable Output (High Impedance)
Output Enable Time	100nSec Maximum
Output Disable Time	50nSec Maximum
Output Enable Current	15mA Maximum (Without Load (Pin 1 = Ground))
RMS Phase Jitter	1.5pSec Maximum (Fj=12kHz to 20MHz (Random))
Period Jitter (Deterministic)	0.2pSec Typical
Period Jitter (Random)	2pSec Typical
Period Jitter (RMS)	3pSec Maximum
Period Jitter (pk-pk)	30pSec Maximum
Start Up Time	10mSec Maximum
Storage Temperature Range	$-55^{\circ}\text{C}$ to $+125^{\circ}\text{C}$

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K

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## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS CONTINUED

<b>Resistance to Solvents</b>	MIL-STD-202, Method 215
<b>Solderability</b>	MIL-STD-883, Method 2003
<b>Temperature Cycling</b>	MIL-STD-883, Method 1010, Condition B
<b>Vibration</b>	MIL-STD-883, Method 2007, Condition A

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### MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Output Enable (OE)
2	Do Not Connect
3	Case/Ground
4	Output
5	Do Not Connect
6	Supply Voltage

LINE	MARKING
1	<b>E18.487</b> <i>E=Ecliptek Designator</i>
2	<b>XXXXX</b> <i>XXXXX=Ecliptek Manufacturing Identifier</i>

### Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

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**OUTPUT WAVEFORM & TIMING DIAGRAM**



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## Test Circuit for CMOS Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C<sub>L</sub> includes sum of all probe and fixture capacitance.

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## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

<b><math>T_s \text{ MAX}</math> to <math>T_L</math> (Ramp-up Rate)</b>	$3^\circ\text{C/Second Maximum}$
<b>Preheat</b>	
- Temperature Minimum ( $T_s \text{ MIN}$ )	$150^\circ\text{C}$
- Temperature Typical ( $T_s \text{ TYP}$ )	$175^\circ\text{C}$
- Temperature Maximum ( $T_s \text{ MAX}$ )	$200^\circ\text{C}$
- Time ( $t_s \text{ MIN}$ )	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_p</math>)</b>	$3^\circ\text{C/Second Maximum}$
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	$217^\circ\text{C}$
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_p</math>)</b>	$260^\circ\text{C Maximum for 10 Seconds Maximum}$
<b>Target Peak Temperature (<math>T_p \text{ Target}</math>)</b>	$250^\circ\text{C} +0/-5^\circ\text{C}$
<b>Time within <math>5^\circ\text{C}</math> of actual peak (<math>t_p</math>)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	$6^\circ\text{C/Second Maximum}$
<b>Time <math>25^\circ\text{C}</math> to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

$T_s$ MAX to $T_L$ (Ramp-up Rate)	5°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_s$ MIN)	N/A
- Temperature Typical ( $T_s$ TYP)	150°C
- Temperature Maximum ( $T_s$ MAX)	N/A
- Time ( $t_s$ MIN)	60 - 120 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	5°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	150°C
- Time ( $t_L$ )	200 Seconds Maximum
<b>Peak Temperature (<math>T_P</math>)</b>	240°C Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	240°C Maximum 2 Times / 230°C Maximum 1 Time
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
<b>Ramp-down Rate</b>	5°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)